[8543	: Electrical...:]	:	:	:
[8543.70	: Other...:]	:	:	:
	: [Other:]	:	:	:
	: [Other:]	:	:	:
8543.70.97	: Plasma cleaner machines that remove	:	:	:
	: organic contaminants from electron	:	:	:
	: microscopy specimens and specimen	:	:	:
	: holders.....	:[See an-	: Free (A,AU,B,	: 35%
	:	: nex II]	: BH,CA,CL,CO,E,	:
	:	:	: IL,JO,KR,MA,	:
	:	:	: MX,OM,P,PA,	:
	:	:	: PE,SG)	:
	:	:	:	:
8543.70.99	: Other.....	: 2.6%	: Free (A,AU,B,	: 35%"
	:	:	: BH,CA,CL,CO,E,	:
	:	:	: IL,JO,KR,MA,	:
	:	:	: MX,OM,P,PA,	:
	:	:	: PE,SG)	:

31. Subheadings 8543.90.11 through 8543.90.88 are deleted and the following new provisions are inserted in lieu thereof:

[8543	:Electrical ...:]	:	:	:
[8543.90	: Parts:]	:	:	:
"8543.90.01	: Goods described in additional U.S. note 14 to	:	:	:
	: this chapter.....	:Free	:	:35%
	:	:	:	:
	: Other:	:	:	:
8543.90.12	: Of physical vapor deposition apparatus of	:	:	:
	: subheading 8543.70.....	:Free	:	:35%
	:	:	:	:
	: Assemblies and subassemblies for flight data	:	:	:
	: recorders, consisting of two or more parts or	:	:	:
	: pieces fastened or joined together:	:	:	:
8543.90.15	: Printed circuit assemblies.....	:Free	:	:35%
	:	:	:	:
8543.90.35	: Other	:Free	:	:35%
	: Other:	:	:	:
	: Printed circuit assemblies:	:	:	:
8543.90.65	: Of flat panel displays other than	:	:	:
	: articles of heading 8528,	:	:	:
	: except for subheadings 8528.51	:	:	:
	: or 8528.61.....	:Free	:	:35%
	:	:	:	:
8543.90.68	: Other	:[See an-	:Free (A,AU,B,	:35%
	:	: nex II]	: BH,CA,CL,CO,	:
	:	:	: E,IL,JO,KR,MA,	:
	:	:	: MX OM,P,PA,	:
	:	:	: PE,SG)	:

8543	:Electrical ...:	:	:	:
[8543.90	: Parts:]	:	:	:
	: [Other:]	:	:	:
	: [Other:]	:	:	:
	: Other:	:	:	:
8543.90.85	: Of flat panel displays other than	:	:	:
	: articles of heading 8528, except	:	:	:
	: for subheadings 8528.51 or	:	:	:
	: 8528.61.....	:Free	:	:35%
	:	:	:	:
8543.90.88	: Other.....	:[See an-	:Free (A,AU,B,	:35%"
	:	: nex II]	: BH,CA,CL,CO,	:
	:	:	: E,IL,JO,KR,MA,	:
	:	:	: MX OM,P,PA,	:
	:	:	: PE,SG)	:

32. The following new additional U.S. note 5 is inserted in numerical sequence in chapter 90:

"5. For purposes of this chapter, the expression "goods described in additional U.S. note 5 to this chapter" are multi-component integrated circuits (MCOs), comprising a combination of one or more monolithic, hybrid, and/or multi-chip integrated circuits with at least one of the following components: silicon-based sensors, actuators, oscillators, resonators or combinations thereof, or components performing the functions of articles classifiable under heading 8532, 8533, 8541, or inductors classifiable under heading 8504, formed to all intents and purposes indivisibly into a single body like an integrated circuit, as a component of a kind used for assembly onto a printed circuit board (PCB) or other carrier, through the connecting of pins, leads, balls, lands, bumps, or pads.

For the purpose of this definition :

1. "Components" may be discrete, manufactured independently then assembled onto the rest of the MCO, or integrated into other components.

2. "Silicon based" means built on a silicon substrate, or made of silicon materials, or manufactured onto integrated circuit die.

3. (a) "Silicon based sensors" consist of microelectronic and/or mechanical structures that are created in the mass or on the surface of a semiconductor and that have the function of detecting physical or chemical quantities and transducing these into electric signals, caused by resulting variations in electric properties or displacement of a mechanical structure. "Physical or chemical quantities" relates to real world phenomena, such as pressure, acoustic waves, acceleration, vibration, movement, orientation, strain, magnetic field strength, electric field strength, light, radioactivity, humidity, flow, chemicals concentration, etc.

(b) "Silicon based actuators" consist of microelectronic and mechanical structures that are created in the mass or on the surface of a semiconductor and that have the function of converting electrical signals into physical movement.